2020-3-18 Rev.3.0

TOSHIBA

RD Number: RD185

RD Title: TB67H450FNG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CN1	1	Terminal block	_	_	PCB terminal block 2 positions		
2	CN2	1	Terminal block	_	_	PCB terminal block 2 positions		
3	CVCC	1	1μF 10V	_	_	Chip capacitor		
4	CVM1	1	1μF 50V	_	_	Chip capacitor		
5	CVM2	1	100µF 50V	_	_	Electrolytic capacitor		
6	CVREF	1	0.1µF 10V	_	_	Chip capacitor		
7	IC1	1	TB67H450FNG	TB67H450FNG	TOSHIBA	DC Brushed Motor Driver IC	HSOP8	
	JP1	1	3 pin header	ı	_	Pin header 3P		
9	JP2	1	3 pin header	_	_	Pin header 3P		
10	JP3	1	3 pin header	_	_	Pin header 3P		
	R1	0	Not mount	_	_	Chip resistor		✓
12	R2	0	Not mount	_	_	Chip resistor		✓
13	RRS1	1	0.22Ω 1W	_	_	Chip resistor		
14	RRS2	1	0.22Ω 1W	_	_	Chip resistor		
15	VM	1	Check terminal	_	_	Check terminal VM		
16	GND	1	Check terminal	_	_	Check terminal GND		
17	VCC	1	Check terminal	_	_	Check terminal VCC		
18	VREF	1	Check terminal		_	Check terminal VREF		
19	IN1	1	Check terminal	_	_	Check terminal IN1		
20	IN2	1	Check terminal	_	_	Check terminal IN2		
21	RS	1	Check terminal	_	_	Check terminal RS		
22	OUT1	1	Check terminal	_	_	Check terminal OUT1		
23	OUT2	1	Check terminal	_	_	Check terminal OUT2		
24	GND	1	Check terminal	_	_	Check terminal GND		
25	GND	1	Check terminal	ı	_	Check terminal GND		
26	VR1	1	100kΩ	_	_	Variable Resistor		
27	C1	0	Not mount		_	Chip capacitor		1
28	C2	0	Not mount	_	_	Chip capacitor		1
29	C3	0	Not mount		_	Chip capacitor		1
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